

Applicable standard					
Rating	Operating temperature range	-35 °C to +85°C (Note1)	Storage temperature range	-10 °C to +60°C (Note3)	
	Operating humidity range	40% to 80% (Note2)	Storage humidity range	40% to 70% (Note3)	
	Applicable connector	DF5A-*S-5C	Current	AWG 18 : 8.0 A	
	Voltage	500 V AC/DC		AWG 20 : 6.0 A AWG 22 : 5.0 A	
Specifications					
Item		Test method	Requirements	QT	AT
Construction					
General examination		Visually and by measuring instrument.	According to drawing.	X	X
Marking		Confirmed visually.		X	X
Electric characteristics					
Contact resistance Millivolt level method		100mA (DC or 1000Hz).	30 mΩ MAX.	X	—
Insulation resistance		500 V DC.	1000 MΩ MIN.	X	—
Voltage proof		1500 V AC for 1 min.	No flashover or breakdown.	X	—
Mechanical characteristics					
Mechanical operation		30 times insertion and extraction.	①Contact resistance: 30 mΩ MAX. ②No damage, crack or looseness of parts.	X	—
Vibration		Frequency 10 to 55Hz, single amplitude 0.75 mm, at 2h, for 3 directions.	①No electrical discontinuity of 10 μ s. ②No damage, crack or looseness of parts.	X	—
Shock		490 m/s ² duration of pulse 11 ms at 3 times for 3 directions.		X	—
Environmental characteristics					
Damp heat (Steady state)		Exposed at 40 ± 2°C , 90 to 95 %, 96 h. (After leaving the room temperature for 1-2h.)	①Contact resistance: 30 mΩ MAX. ②Insulation resistance: 500 MΩ MIN. ③No damage, crack or looseness of parts.	X	—
Rapid change of temperature		Temperature -55 →5 to 35→ 85 →5 to 35 °C Time 30 → 5 → 30 → 5 min Under 5 cycles.	①Contact resistance: 30 mΩ MAX. ②Insulation resistance: 1000 MΩ MIN. ③No damage, crack or looseness of parts.	X	—
Resistance to soldering heat		[Recommended temperature profile] Solder temperature 260±3°C for immersing duration 10±1s. [Recommended manual soldering condition] Soldering iron temperature:350±5°C for within 3±1s No strength on contact.	No deformation on case or excessive looseness of the terminals.	X	—
Solderability		Soldered at solder temperature : 235°C For in immersing duration : 5s.	New uniform coating of solder shall cover minimum of 95 % of the surface being immersed.	X	—
Remarks Note 1:Include the temperature rising by current. Note 2:No condensing Note 3:Apply to the condition of long term storage for unused products before pcb on board, after pcb on board, operating temperature and humidity range is applied for interim storage during transportation.					
	Count	Description of revisions	Designed	Checked	Date
①					
Unless otherwise specifid , refer to IEC 60512.			Approved	KI. AKIYAMA	15. 08. 19
			Checked	TS. FUKUSHIMA	15. 08. 19
			Designed	MI. SAKIMURA	15. 08. 19
			Drawn	MI. SAKIMURA	15. 08. 19
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			Drawing no.		ELC-160242-35-00
HRS	Specification sheet		Part no.	DF5A-*P-5DSA (35)	
	Hirose electric co., Ltd.		Code no.	CL676-	① 1/1